

L Number	Hits	Search Text	DB	Time stamp
4	23	probe with (conductive adj layer) with (silver or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 16:58
5	39184	core with steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 16:59
6	1083	(core with steel) and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 16:59
7	1976	(core adj wire) with steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 16:59
8	98	((core adj wire) with steel) and ((core with steel) and probe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 16:59
11	12	(((((core adj wire) with steel) and ((core with steel) and probe)) and (silver or copper)) and nickel) and gold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 17:00
10	19	(((((core adj wire) with steel) and ((core with steel) and probe)) and (silver or copper)) and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 17:02
9	63	((((core adj wire) with steel) and ((core with steel) and probe)) and (silver or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/12 17:04
-	11996	conductive near3 coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:30
-	8	(conductive near3 coil) and 324/754.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:25
-	1038	(conductive near3 coil) and 324/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:26
-	33	(conductive near3 coil) and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:27
-	4785	probe near5 coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:28
-	357	(probe near5 coil) with contact\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:29

-	7	"6043666"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:31
-	3755	kazama.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:31
-	34	kazama.in. and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:35
-	34	kazama.in. and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:35
-	104	(probe near5 coil) and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:40
-	76	kazama.in. and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:45
-	3405	probe near3 coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:45
-	309	(probe near3 coil) with conduct\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:46
-	450288	conductive near3 coil nea5 taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:56
-	450288	(conductive near3 coil) nean5 taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:56
-	11	(conductive near3 coil) near5 taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 18:58
-	30	(conductive near3 coil) with taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:00
-	62105	coil near5 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:00
-	1498	(conductive near3 coil) with (coil near5 wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:00

-	98	((conductive near3 coil) with (coil near5 wire)) and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:04
-	34300	turn near3 coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:04
-	185	(turn near3 coil) with probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11 19:05
-	922	coil near5 taper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:21
-	12840	324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:45
-	25	324/750-765,158.1.ccls. and coil and taper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:23
-	798	324/750-765,158.1.ccls. and coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:37
-	284	(324/750-765,158.1.ccls. and coil) and smaller	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:24
-	408	(324/750-765,158.1.ccls. and coil) and turn\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:37
-	2512	324/750-765,158.1.ccls. and turn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:45
-	1755	(324/750-765,158.1.ccls. and turn) and contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 13:45
-	12958	conductive near3 coil	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:30
-	0	(conductive near3 coil) and tapper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:30
-	2	((conductive near3 coil) and (core adj wire)) and 324/754-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:31

-	104	(conductive near3 coil) and (core adj wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:35
-	44	(conductive adj2 layer) near5 (core adj wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:36
-	4	("5200695" "5225773" "5461326" "5865632").PN.	USPAT	2003/12/08 14:48
-	4766	385/\$.ccls. and (probe or tip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:58
-	94	(conduct\$4 near layer) and (385/\$.ccls. and (probe or tip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 15:30
-	2367	(conduct\$4 near layer) and 324/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 15:40
-	585	((conduct\$4 near layer) and 324/\$.ccls.) and (probe or tip) and test\$4 near5 (semiconductor or chip or integrated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 15:31
-	602	(conduct\$4 near layer) and 324/754-761.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 15:40
-	488	((conduct\$4 near layer) and 324/754-761.ccls.) and (probe or tip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 15:40
-	273	((conduct\$4 near layer) and 324/754-761.ccls.) and (probe or tip) and (coil or spring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 16:42
-	3	("4731577" "5557212" "5969533").PN.	USPAT	2003/12/08 16:30
-	3	("6452406").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 16:51
-	57	(core adj wire) with (conductive adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 16:52
-	24	((core adj wire) with (conductive adj layer)) and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 16:52